



Specification for Approval

Date: 2018/11/29

ECI2012TE_SEDIES





深圳台慶 Customer:

	TAI-TECH P/N:	FCI2012TF-SERIES	8				
	CUSTOMER P/N:						
	DESCRIPTION:						
	QUANTITY:	pcs	; _				
REM	IARK:						
	0	-t A -	1-				
	Cu	stomer Approval Feedba	ICK				

西北臺慶科技股份有限公司 TAI-TECH Advanced Electronics Co., Ltd

□西北臺慶科技股份有限公司

TAI-TECH Advanced Electronics Co., Ltd Headquarter:

NO.1 YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN HSIEN, TAIWAN, R.O.C.

TEL: +886-3-4641148 FAX: +886-3-4643565

http://www.tai-tech.com.tw E-mail: sales@tai-tech.com.tw

□Office:

11BC, Building B Fortune Plaza, NO. 7002, Shennan Avenue, Futian District Shenzhen

TEL: +86-755-23972371 FAX: +86-755-23972340

■臺慶精密電子(昆山)有限公司

TAI-TECH ADVANCED ELECTRONICS(KUNSHAN) CO., LTD SHINWHA ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA TEL: +86-512-57619396 FAX: +86-512-57619688

E-mail: sales@tai-tech.cn

□慶邦電子元器件(泗洪)有限公司

TAIPAQ ELECTRONICS (SIHONG) CO., LTD JIN SHA JIANG ROAD , CONOMIC DEVELOPMENT ZONE SIHONG , JIANGSU , CHINA.
TEL: +86-527-88601191 FAX: +86-527-88601190

E-mail: sales@taipaq.cn

Sales Dep.

APPROVED	CHECKED
管哲頎	劉瑷瑄
Eric Guan	Aries Liu

R&D Center

APPROVED	CHECKED	DRAWN	
鄧福興	浦冬生	王俞琴	

Ferrite Chip Inductor(Lead Free)

FCI2012TF-SERIES

ECN HISTORY LIST									
REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN				
1.0	13/06/06	變更可靠度條件	楊祥忠	羅培君	張嘉玲				
2.0	14/01/24	變更電鍍錫層厚度 3.0um min.=>3.5um min.	楊祥忠	羅培君	張嘉玲				
3.0	14/08/01	變更 Reflow 圖示	楊祥忠	羅培君	張嘉玲				
3.1	14/08/01	修正包裝帶尺寸	楊祥忠	羅培君	張嘉玲				
4.0	16/01/26	修訂可靠度 Life Test: (Inductor) Temperature:85±2℃ →105±2℃.	楊祥忠	詹偉特	張嘉玲				
5.0	17/02/16	修訂 Recommended PC Board Pattern	楊祥忠	詹偉特	張嘉玲				
備		1							
註									

TAI-TECH KBM01-181100680 P2.

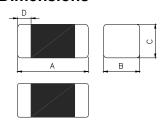
Ferrite Chip Inductor(Lead Free)

FCI2012F-SERIES

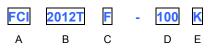
1.Features

- 1. Monolithic inorganic material construction.
- 2. Closed magnetic circuit avoids crosstalk.
- 3. S.M.T. type.
- 4. Suitable for reflow soldering.
- 5. Shapes and dimensions follow E.I.A. spec.
- 6. Available in various sizes.
- 7. Excellent solder ability and heat resistance.
- 8. High reliability.
- 9.100% Lead(Pb) & Halogen-Free and RoHS compliant.
- 10. Operating Temperature: -55~+105°C (Including self-temperature rise)

2. Dimensions



3. Part Numbering



A: Series

B: Dimension L x W

C: Material Lead Free Material

D: Inductance 100=10.0uH

E: Inductance Tolerance K=±10%, M=±20%

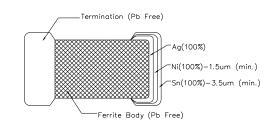
Halogen-free





Chip Size						
Α	2.00±0.20					
В	1.25±0.20					
С	0.85±0.20					
D	0.50±0.30					

Units: mm



4. Specification

Tai-Tech	Inductance(uH)		Q		Rated Current	DCR	SRF
Part Number	Tolerance	Test Frequency (Hz)	min.	Test Frequency (MHz)	(mA) max.	(Ω) max.	(MHz) min.
FCI2012TF-2R7	2.7	60mV / 10M	45	10	30	0.75	45
FCI2012TF-3R3	3.3	60mV / 10M	45	10	30	0.80	41
FCI2012TF-4R7	4.7	60mV / 10M	45	10	30	1.00	35
FCI2012TF-100	10.0	60mV / 2M	45	2	15	1.15	24

NOTE: \square :TOLERANCE K= \pm 10%, L= \pm 15%, M= \pm 20%

- Rated current: based on temperature rise test
- In compliance with EIA 595

TAI-TECH KBM01-181100680 P4.

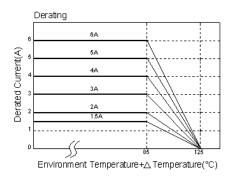
5. Reliability and Test Condition

Item		Performance			Tes	st Cond	dition	
Series No.	FCI	FHI FCH	HCI					
Operating Temperature		-55∼+105 $^{\circ}$ C (Including self-temperature rise)						
Transportation Storage Temperature		-55~+105°C (on board)		For long Application	·		ns, please	see the
inductance (Ls)				Agilent42 Agilent E				
Q Factor	Refer to standard	electrical characteristics list		Agilent42 Agilent16				
DC Resistance				Agilent 43	338			
Rated Current			DC Powe Over Rate some risk	ed Curr		ements, the	re will be	
Temperature Rise Test	Rated Current < 1A Rated Current ≧ 1A				rature n	owed DC neasured	current. by digital s	urface
Life test	Appearance: no c	amage. n±15%of initial value.		times.(IP Reflow Pr Temperat Applied of Duration: Measured for 24±2 h	PC/JEDE rofiles) cure: 10: current: 1 1000±1 d at rochrs.	EC J-STD 5±2℃ rated curre I2hrs. om tempe	rature afte	ssification
Load Humidity	Q : Shall not exce	±10%of initial value. sed the specification value. % of initial value and shall not exceed the	specification value	Preconditioning: Run through IR reflow times.(IPC/JEDEC J-STD-020D Classific Reflow Profiles) Humidity: 85±2%R.H. Temperature: 85±2°C. Duration: 1000hrs Min. with 100% ocurrent. Measured at room temperature after pla for 24±2 hrs.			ssification % rate	
Thermal shock	Impedance: within Inductance: within Q: Shall not exce	Appearance: no damage. Impedance: within±15%of initial value. Inductance: within±10%of initial value. Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the specification value				Preconditioning: Run through IR reflow for 2 times. (IPC/LIDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1: -55±2°C 30±5 min. Step2: 25±2°C ≤0.5min Step3: +105±2°C 30±5min. Number of cycles: 500 Measured at room temperature after placing for 24±2 hrs.		
Vibration	Inductance : with Q : Shall not exce	damage. in±15% of initial value n±10% of initial value sed the specification value. % of initial value and shall not exceed the	specification value	Preconditioning: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profiles) Oscillation Frequency: 10~2K~10Hz for 20 minutes Equipment: Vibration checker Total Amplitude:1.52mm±10% Testing Time: 12 hours(20 minutes, 12 cycles each of 3 orientations)				
Bending	Inductance : with Q : Shall not exce	damage. in±10% of initial value n±10% of initial value sed the specification value. % of initial value and shall not exceed the	specification value	following >=0805in <0805incl Bending o >=0805incl	dimens ch(2012 h(2012) depth: ch(2012) h(2012)	ions: 2mm):40x	m	
Shock	Inductance : with	damage. in±10% of initial value n±10% of initial value eed the specification value.		Test con	Peak Value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec
		% of initial value and shall not exceed the	specification value	Lead	50	11	Half-sine	11.3
Insulation Resistance	IR>1GΩ			_	age:100	±10%V fo	r 30Sec.	
Solderability More than 95% of the terminal electrode should be covered with solder. More than 95% of the terminal electrode should be covered with solder. Preheat: 150°C,60sec. Solder: Sn96.5%-Ag3%-Cu0.5 Solder temperature: 245±5°C Flux for lead free: Rosin. 9.5% Depth: completely cover the te Dip time: 4±1sec.					°℃ .5%	on.		

Item	Performance	Test Condition			
		Number of heat	cycles: 1		
Resistance to Soldering	Appearance : No damage. Impedance : within±15% of initial value		Temperature (°C)	Time (s)	Temperature ramp/immersion and emersion rate
Heat	Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within ±15% of initial value and shall not exceed the sp	260 ±5 (solder temp)	10 ±1	25mm/s ±6 mm/s	
			Depth: complete	ely cover t	he termination
Terminal strength	Appearance: No damage. Impedance: within±15% of initial value Inductance: within±10% of initial value Q: Shall not exceed the specification value. RDC: within±15% of initial value and shall not exceed the specification value	wide thickness shear force	Preconditioning: Run through IR reflow for times.(IPC/JEDEC J-STD-020D Classificatio Reflow Profiles) Component mounted on a PCB apply a forc >0805inch(2012mm):1kg c=0805inch(2012mm):0.5kg to the side of a device being tested. This forc shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to shoot the component being tested.		

**Derating Curve

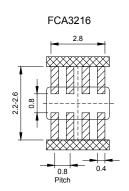
For the ferrite chip bead which withstanding current over 1.5A, as the operating temperature over $85^{\circ}\mathrm{C}$, the derating current information is necessary to consider with. For the detail derating of current, please refer to the Derated Current vs. Operating Temperature curve.



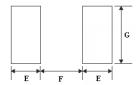
6. Soldering and Mounting

6-1. Recommended PC Board Pattern

		Land Patterns For Reflow Soldering						
Series	Type	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)	F(mm)	G(mm)
	0603	0.6±0.03	0.30±0.03	0.30±0.03	0.15±0.05	0.35	0.30	0.40
FCB	1005	1.0±0.10	0.50±0.10	0.50±0.10	0.25±0.10	0.50	0.40	0.60
FCM	1608	1.6±0.15	0.80±0.15	0.80±0.15	0.30±0.20	0.80	0.85	0.95
нсв	2012	<mark>2.0±0.20</mark>	<mark>1.25±0.20</mark>	<mark>0.85±0.20</mark>	0.50±0.30	1.05	1.00	1.45
GHB	2012	2.0±0.20	1.25±0.20	1.25±0.20	0.50±0.30	1.05		
<mark>FCI</mark> FHI	3216	3.2±0.20	1.60±0.20	1.10±0.20	0.50±0.30	1.05	2.20	1.80
FCH	3225	3.2±0.20	2.50±0.20	1.30±0.20	0.50±0.30	1.05	2.20	2.70
HCI	4516	4.5±0.20	1.60±0.20	1.60±0.20	0.50±0.30	1.05	3.30	1.80
1101	4532	4.5±0.20	3.20±0.20	1.50±0.20	0.50±0.30	1.05	3.30	3.40



∠∠∠ Land Solder Resist



PC board should be designed so that products can prevent damage from mechanical stress when warping the board.

6-2. Soldering

Mildly activated rosin fluxes are preferred. The terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools. Note.

If wave soldering is used ,there will be some risk.

Re-flow soldering temperatures below 240 degrees, there will be non-wetting risk

TAI-TECH KBM01-181100680 P6.

6-2.1 Lead Free Solder re-flow:

Recommended temperature profiles for lead free re-flow soldering in Figure 1. (Refered to J-STD-020C)

6-2.2 Soldering Iron:

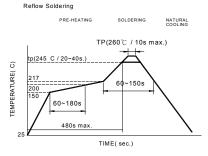
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. If a soldering iron must be employed the following precautions are recommended. for Iron Soldering in Figure 2.

• 350°C tip temperature (max)

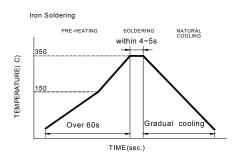
Never contact the ceramic with the iron tip

• 1.0mm tip diameter (max)

- Use a 20 watt soldering iron with tip diameter of 1.0mm
- Limit soldering time to 4~5sec.



Reflow times: 3 times max Fig.1

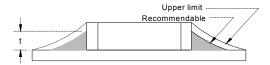


Iron Soldering times: 1 times max

6-2.3 Solder Volume:

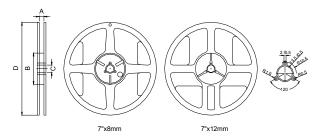
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceed as shown in right side:

Minimum fillet height = soldering thickness + 25% product height



7. Packaging Information

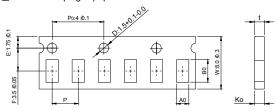
7-1. Reel Dimension

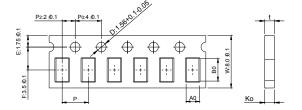


Туре	A(mm)	B(mm)	C(mm)	D(mm)	
<mark>7"x8mm</mark>	9.0±0.5	60±2	13.5±0.5	<mark>178±2</mark>	
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2	

7-2.1 Tape Dimension / 8mm

■Material of taping is paper



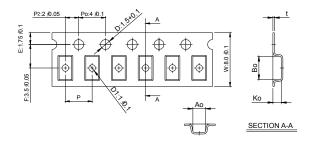


Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
060303	0.70±0.06	0.40±0.06	0.45max	2.0±0.05	0.45max
100505	1.12±0.03	0.62±0.03	0.60±0.03	2.0±0.05	0.60±0.03

Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)
160808	1.80±0.05	0.96+0.05/-0.03	0.95±0.05	4.0±0.10	0.95±0.05
<mark>201209</mark>	<mark>2.10±0.05</mark>	1.30±0.05	<mark>0.95±0.05</mark>	4.0±0.10	0.95±0.05

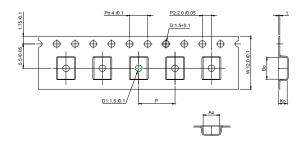
TAI-TECH KBM01-181100680 P7.

■Material of taping is plastic



Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
201212	2.10±0.10	1.28±0.10	1.28±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321611	3.35±0.10	1.75±0.10	1.25±0.10	4.0±0.10	0.23±0.05	1.0±0.10
322513	3.42±0.10	2.77±0.10	1.55±0.10	4.0±0.10	0.22±0.05	1.0±0.10
321609	3.40±0.10	1.77±0.10	1.04±0.10	4.0±0.10	0.22±0.05	1.0±0.10

7-2.2 Tape Dimension / 12mm

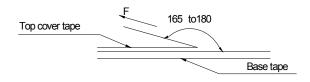


	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	t(mm)	D1(mm)
	451616	4.70±0.10	1.75±0.10	1.75±0.10	4.0±0.10	0.24±0.05	1.5±0.10
•	453215	4.70±0.10	3.45±0.10	1.60±0.10	8.0±0.10	0.24±0.05	1.5±0.10

7-3. Packaging Quantity

Chip Size	453215	451616	322513	321611	321609	201212	<mark>201209</mark>	160808	100505	060303
Chip / Reel	1000	2000	2500	3000	3000	2000	<mark>4000</mark>	4000	10000	15000
Inner box	4000	8000	12500	15000	15000	10000	<mark>20000</mark>	20000	50000	75000
Middle box	20000	40000	62500	75000	75000	50000	100000	100000	250000	375000
Carton	40000	80000	125000	150000	150000	100000	200000	200000	500000	750000

7-4. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

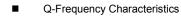
Room Temp.	Room Humidity	Room atm	Tearing Speed	
(℃)	(%)	(hPa)	mm/min	
5~35	45~85	860~1060	300	

Application Notice

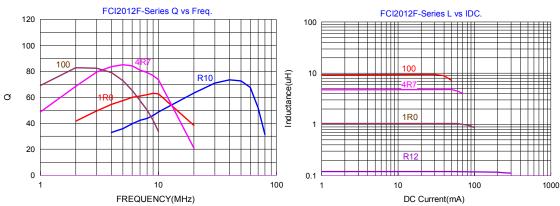
- Storage Conditions(component level)
- To maintain the solder ability of terminal electrodes:
- 1. TAI-TECH products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
- 2. Temperature and humidity conditions: Less than 40°C and 60% RH.
- 3. Recommended products should be used within 12 months from the time of delivery.
- 4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
- 1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
- 2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
- 3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

TAI-TECH KBM01-181100680 P8.

Typical Impedance v.s. Frequency Curve









Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 1 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

以下測試樣品係由申請廠商所提供及確認 (The following sample(s) was/were submitted and identified by/on behalf of the applicant as):

樣品名稱(Sample Description)

: FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

樣品型號(Style/Item No.)

FERRITE CHIP BEAD INDUCTOR ARRAY MCF MCM YMV SERIES

收件日期(Sample Receiving Date)

2017/12/05

測試期間(Testing Period)

2017/12/05 TO 2017/12/12

測試結果(Test Results) :

請參閱下一頁 (Please refer to following pages).

Signed for and on being SGS TAIWAN LTD. Chemical Laboratory - Taipei

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions for Electronic Documents at http://www.sgs.com/en/Terms-and-Conditions/Ferms-a



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 2 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試結果(Test Results)

測試部位(PART NAME)No.1

: 整體混測(MIXED ALL PARTS)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鍋 / Cadmium (Cd)	mg/kg	參考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
鉛 / Lead (Pb)	mg/kg	参考IEC 62321-5 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-5 (2013) and performed by ICP-AES.	2	n. d.
汞 / Mercury (Hg)	mg/kg	参考IEC 62321-4 (2013),以感應耦合 電漿原子發射光譜儀檢測. / With reference to IEC 62321-4 (2013) and performed by ICP-AES.	2	n. d.
六價絡 / Hexavalent Chromium Cr(VI) (◆)	mg/kg	参考IEC 62321-7-2 (2017),以UV-VIS 檢測;参考IEC 62321-5 (2013),以 ICP-AES檢測. / With reference to IEC 62321-7-2 (2017) and performed by UV-VIS.; With reference to IEC 62321-5 (2013) and performed by ICP-AES.	8	n. d.
绨 / Antimony (Sb)	mg/kg	参考US EPA 3052 (1996),以感應耦合 電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.aus.com/en/Tems.aud-Conditions for electronic format documents, subject to Terms and Conditions for Electronic Documents at https://www.aus.com/en/Tems.aud-Conditions/ femas-Document assay. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document: s unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 3 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO, LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
砷 / Arsenic (As)	mg/kg	参考US EPA 3052 (1996),以感應耦合電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.
皴 / Beryllium (Be)	mg/kg	参考US EPA 3052 (1996),以感應耦合電漿原子發射光譜儀檢測. / With reference to US EPA 3052 (1996). Analysis was performed by ICP-AES.	2	n. d.
全氟辛烷磺酸 / Perfluorooctane sulfonates (PFOS-Acid, Metal Salt, Amide)	mg/kg	参考US EPA 3550C (2007),以液相層 析/質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n, d,
全氟辛酸 / PFOA (CAS No.: 335-67-1)	mg/kg	參考US EPA 3550C (2007),以液相層 析/質譜儀檢測. / With reference to US EPA 3550C (2007). Analysis was performed by LC/MS.	10	n. d.
聚氯乙烯 / PVC	**	以紅外光譜分析及焰色法檢測. / Analysis was performed by FTIR and FLAME Test.	_	Negative
鄰苯二甲酸丁苯甲酯 / BBP (Butyl Benzyl phthalate) (CAS No.: 85-68-7)	mg/kg	# HDC 60001 0 (0017)	50	n, d.
鄰苯二甲酸二丁酯 / DBP (Dibuty1 phthalate) (CAS No.: 84-74-2)	mg/kg	参考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was	50	n. d.
鄰苯二甲酸二 (2-乙基己基)酯 / DEHP (Di- (2-ethylhexyl) phthalate) (CAS No.: 117-81-7)	mg/kg	performed by GC/MS.	50	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sus.com/ep/Temise-200m/ep/Temise-20



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 4 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鄰苯二甲酸二異丁酯 / DIBP (Di- isobutyl phthalate) (CAS No.: 84-69- 5)	mg/kg		50	n. d.
鄰苯二甲酸二異癸酯 / DIDP (Di- isodecyl phthalate) (CAS No.: 26761- 40-0; 68515-49-1)	mg/kg		50	n. d.
鄰苯二甲酸二異壬酯 / DINP (Di- isononyl phthalate) (CAS No.; 28553- 12-0; 68515-48-0)	mg/kg	參考IEC 62321-8 (2017),以氣相層析 儀/質譜儀檢測. / With reference to IEC 62321-8 (2017). Analysis was	50	n. d.
鄰苯二甲酸二正辛酯 / DNOP (Di-n-octyl phthalate) (CAS No.: 117-84-0)	mg/kg	performed by GC/MS.	50	n. d.
鄰苯二甲酸二正己酯 / DNHP (Di-n-hexyl phthalate) (CAS No.: 84-75-3)	mg/kg		50	n. d.
鄰苯二甲酸二戊酯 / Di-n-pentyl phthalate (CAS No.: 131-18-0)	mg/kg		50	n. d.
六溴環十二烷及所有主要被辨別出的異構物 / Hexabromocyclododecane (HBCDD) and all major diastereoisomers identified (α - HBCDD, β - HBCDD, γ - HBCDD) (CAS No.: 25637-99-4 and 3194-55-6 (134237-51-7, 134237-50-6, 134237-52-8))	mg/kg	参考IEC 62321 (2008),以氣相層析/ 質譜儀檢測. / With reference to IEC 62321 (2008). Analysis was performed by GC/MS.	5	n. d.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <a href="https://www.ags.con/ee/Farms-and-Conditions-Service-Prints-And-Conditions-Service-Prints-And-Conditions-Service-Prints-And-Conditions-Service-Prints-And-Conditions-Prints-And-Condit



Test Report

號碼(No.): CE/2017/C0633 日期(Date): 2017/12/12

頁數(Page): 5 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

測試項目 (Test Items)	單位 (Unit)	测試方法 (Method)	方法偵測 極限值 (MDL)	結果 (Result) No.1
多溴聯苯總和 / Sum of PBBs	mg/kg			n. d.
一溴聯苯 / Monobromobiphenyl	mg/kg	Ī	5	n. d.
二溴聯苯 / Dibromobiphenyl	mg/kg	Ι Γ	5	n, d.
三溴聯苯 / Tribromobiphenyl	mg/kg	1 Γ	5	n, d,
四溴聯苯 / Tetrabromobiphenyl	mg/kg]	5	n, d,
五溴聯苯 / Pentabromobiphenyl	mg/kg		5	n. d.
六溴聯苯 / Hexabromobiphenyl	mg/kg		5	n. d.
七溴聯苯 / Heptabromobiphenyl	ng/kg		5	n. d.
八溴聯苯 / Octabromobiphenyl	mg/kg		5	n, d.
九溴聯苯 / Nonabromobiphenyl	mg/kg	】参考IEC 62321-6 (2015),以氣相層析 □	5	n. d.
十溴聯苯 / Decabromobiphenyl	mg/kg	/質譜儀檢測. / With reference to	5	n. d.
多溴聯苯醚總和 / Sum of PBDEs	mg/kg	IEC 62321-6 (2015) and performed	***	n, d.
一溴聯苯醚 / Monobromodiphenyl ether	mg/kg	by GC/MS.	5	n. d.
二溴聯苯醚 / Dibromodiphenyl ether	mg/kg		5	n. d.
三溴聯苯醚 / Tribromodiphenyl ether	ng/kg		5	n. d.
四溴聯苯醚 / Tetrabromodiphenyl ether	mg/kg		5	n, d.
五溴聯苯醚 / Pentabromodiphenyl ether	mg/kg		5	n. d.
六溴聯苯醚 / Hexabromodiphenyl ether	mg/kg		5	n. d.
七溴聯苯醚 / Heptabromodiphenyl ether	mg/kg]	5	n. d.
八溴聯苯醚 / Octabromodiphenyl ether	mg/kg	Ι	5	n. d.
九溴聯苯醚 / Nonabromodiphenyl ether	mg/kg] Γ	5	n, d,
十溴聯苯醚 / Decabromodiphenyl ether	mg/kg		5	n. đ.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.aus.com/en/Tema-and-Conditions.gagge and, for electronic format documents, subject to Terms and Conditions for Electronic Documents at httention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and writhin the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 6 of 16

Test Report

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P,R, CHINA)

测試項目 (Test Items)	單位 (Unit)	測試方法 (Method)	方法偵測 極限値 (MDL)	結果 (Result) No.1
鹵素 / Halogen			,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	NO. I
鹵素(氟)/ Halogen-Fluorine (F) (CAS No.: 14762-94-8)	mg/kg		50	n. d.
鹵素(氣)/ Halogen-Chlorine (C1) (CAS No.: 22537-15-1)	mg/kg	参考BS EN 14582 (2016),以離子層析 儀分析. / With reference to BS EN	50	n. d.
鹵素(溴)/ Halogen-Bromine (Br) (CAS No.: 10097-32-2)	mg/kg	14582 (2016). Analysis was performed by IC.	50	n. d.
鹵素(碘)/ Halogen-Iodine(I)(CAS No.: 14362-44-8)	mg/kg		50	n. d.

備註(Note):

- 1. mg/kg = ppm ; 0.1wt% = 1000ppm
- 2. n.d. = Not Detected (未檢出)
- 3. MDL = Method Detection Limit (方法偵測極限值)
- 4. "-" = Not Regulated (無規格值)
- 5. **= Qualitative analysis (No Unit) 定性分析(無單位)
- 6. Negative = Undetectable 陰性(未偵測到); Positive = Detectable 陽性(已偵測到)

7. (�):

若鉻含量小於六價鉻之方法偵測極限值,則六價鉻為n,d,,不須再測試六價鉻。

The result of Cr(VI) is "n.d." as the result of Chromium (Cr) is less than the MDL of Cr(VI), and confirmation test of Cr(VI) is not required.

若鉻含量未小於六價鉻之方法偵測極限值,需進行六價鉻測試。

If the Chromium (Cr) content is not less than the MDL of Cr(VI), confirmation test of Cr(VI) is required.

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <a href="https://document.spx.com/anflorms.and-Conditions.for-Incompany-And-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-Administrations.for-Incompany-and-Conditions.for-Incompany-and-Conditions.for-Incompany-Administrations.for-Incompany-and-Conditions.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.for-Incompany-Administrations.



Test Report

號碼(No.): CE/2017/C0633 日期(Date): 2017/12/12

頁數(Page): 7 of 16

I DE LE TOUR BLUE DE LE TOUR FORMEN DE LE TOUR DE LE TO

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

8. 樣品的測試是基於申請人要求混合測試,報告中的混合測試結果不代表其中個別單一材質的含量. (The samples was/were analyzed on behalf of the applicant as mixing sample in one testing. The above results was/were only given as the informality value.)

PFOS參考資訊(Reference Information): 持久性有機污染物 POPs - (EU) 757/2010

PFOS濃度在物質或製備中不得超過0.001%(10ppm),在半成品、成品或零部件中不得超過0.1%(1000ppm),在紡織品或塗 層材料中不得超過1ug/m2。

(Outlawing PFOS as substances or preparations in concentrations above 0.001% (10ppm), in semi-finished products or articles or parts at a level above 0.1%(1000ppm), in textiles or other coated materials above lug/m^2 .)

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions-fems-a-Documents-sess. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 8 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市筵朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

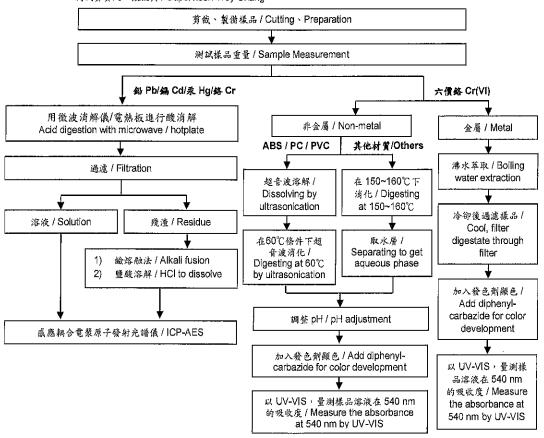
(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R, CHINA)

<u>重金屬流程圖 / Analytical flow chart of Heavy Metal</u>

根據以下的流程圖之條件,樣品已完全溶解。(六價鉻測試方法除外)

These samples were dissolved totally by pre-conditioning method according to below flow chart. (Cr6+ test method excluded)

- 測試人員:王志瑋 / Technician : JR Wang
- 测試負責人:張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.sqs.com/en/Terms-act-Conditions.asce. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, Any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 9 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

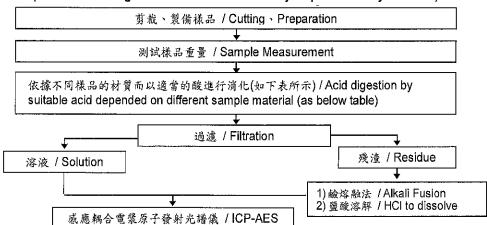
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P,R, CHINA)

根據以下的流程圖之條件,樣品已完全溶解。 / These samples were dissolved totally by pre-conditioning method according to below flow chart.

- 測試人員:王志瑋 / Technician: JR Wang
- 測試負責人:張啟興 / Supervisor: Troy Chang

元素以 ICP-AES 分析的消化流程圖 (Flow Chart of digestion for the elements analysis performed by ICP-AES)



	_
鋼,銅,鋁,焊錫 / Steel, copper, aluminum, solder	王水,硝酸,鹽酸,氫氟酸,雙氧水 /
	Aqua regia, HNO₃, HCl, HF, H₂O₂
玻璃 / Glass	硝酸,氫氟酸 / HNO3/HF
金,鉑,鈀,陶瓷 / Gold, platinum, palladium, ceramic	王水 / Aqua regia
銀 / Silver	硝酸 / HNO3
塑膠 / Plastic	硫酸,雙氧水,硝酸,鹽酸 / H2SO4, H2O2, HNO3, HCI
其他 / Others	加入適當的試劑至完全溶解 / Added appropriate
	reagent to total digestion

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <a href="http://www.ags.com/en/Terms-and-Conditions-for-lectronic Documents at <a href="http://www.ags.com/en/Terms-and-Conditions-for-lectronic Documents at <a href="http://www.ags.com/en/Terms-and-Conditions-for-lectronic Documents at <a href="http://www.ags.com/en/Terms-and-Conditions-for-lectronic-bocuments-for-lectr



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 10 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

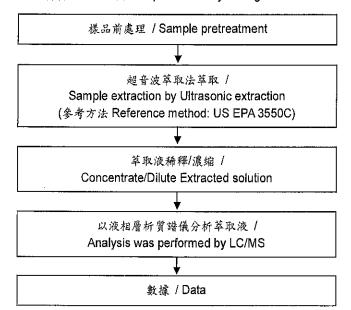
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU,

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R. CHINA)

全氟辛酸/全氟辛烷磺酸分析流程圖 / Analytical flow chart - PFOA/PFOS

■ 測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at <a href="http://www.sus.com/en/Terms-and-Conditions-for-send-Condi



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 11 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

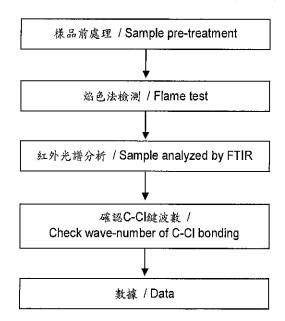
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

聚氯乙烯物質判定分析流程圖 / Analysis flow chart - PVC

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.sgs.com/en/Terms-and-Conditions-and-Condit



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 12 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號 (NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU,

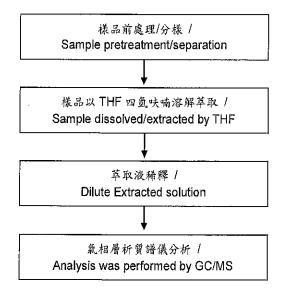
(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

<u>可塑劑分析流程圖 / Analytical flow chart - Phthalate</u>

測試人員:徐毓明 / Technician: Andy Hsu

測試負責人:張啟興 / Supervisor: Troy Chang

【测試方法/Test method: IEC 62321-8】



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.ags.cor/en/Terms-and-Conditions.cor/en/Terms-and-C



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 13 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO, LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

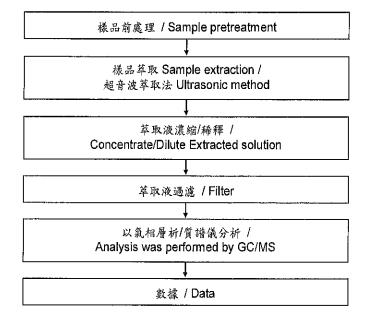
桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

六溴環十二烷分析流程圖 / Analytical flow chart - HBCDD

- 測試人員:涂雅苓 / Technician: Yaling Tu
- 測試負責人:張啟興 / Supervisor: Trov Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://prov.sgs.com/en/Terms-and-Conditions. Attention is drawn to the limitation of liability, indemnification and jurisdiction issues defined therein. Any holder of this document is advised that information contained hereon reflects the Company's findings at the time of its intervention only and within the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents. This document cannot be reproduced, except in full, without prior written approval of the Company, any unauthorized alteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 14 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD,KUNJIA HI-TECH INDUSTRIAL PARK,KUN-SHAN,JIANG-SU, CHINA)

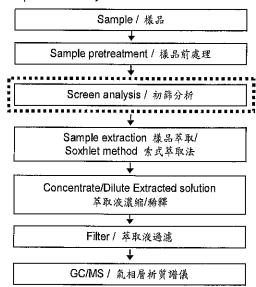
(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P, R, CHINA)

<u>多溴聯苯/多溴聯苯醚分析流程圖 / Analytical flow chart - PBB/PBDE</u>

測試人員:涂雅苓 / Technician: Yaling Tu

測試負責人:張啟興 / Supervisor: Troy Chang

初次测試程序 / First testing process _ 選擇性篩檢程序 / Optional screen process •••••• 確認程序 / Confirmation process - - - →



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://rewww.2gs.com/en/Tamis-ant-Conditions for electronic format documents, subject to Terms and Conditions for Electronic Documents at http://rewww.ggs.com/en/Tamis-ant-Conditions/ entertained hereon reflects the Company's findings at the time of its intervention only and writin the limits of client's instruction, if any. The Company's sole responsibility is to its Client and this document does not exonerate parties to a transaction from exercising all their rights and obligations under the transaction documents, This document cannot be reproduced, except in full, without prior written approval of the Company, any unauthorized atteration, forgery or falsification of the content or appearance of this document is unlawful and offenders may be prosecuted to the fullest extent of the law. Unless otherwise stated the results shown in this test report refer only to the sample(s) tested.



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 15 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件(泗洪)有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

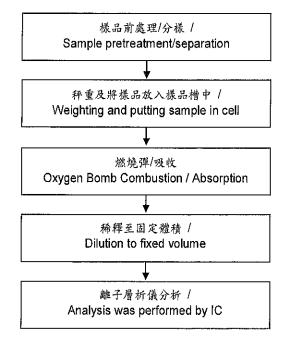
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU, CHINA)

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R, CHINA)

鹵素分析流程圖 / Analytical flow chart - Halogen

測試人員: 陳恩臻 / Technician: Rita Chen

測試負責人:張啟興 / Supervisor: Troy Chang



This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at http://www.ags.com/en/Temps-and-Conditions-Service and Conditions for Electronic Documents at <a href="http://www.ags.com/en/Temps-and-Conditions-Document-service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-Conditions-Service-and-C



Test Report

號碼(No.): CE/2017/C0633

日期(Date): 2017/12/12

頁數(Page): 16 of 16

西北臺慶科技股份有限公司 / TAI-TECH ADVANCED ELECTRONICS CO., LTD.

(臺慶精密電子(昆山)有限公司 / TAI-TECH ADVANCED ELECTRONICS (KUN-SHAN) CO. LTD.)

(慶邦電子元器件 (泗洪) 有限公司 / TAIPAQ ELECTRONICS (SI-HONG) CO., LTD.)

桃園市楊梅區幼獅工業區幼四路1號(NO. 1, YOU 4TH ROAD, YOUTH INDUSTRIAL DISTRICT, YANG-MEI, TAO-YUAN CITY, TAIWAN, R. O. C.)

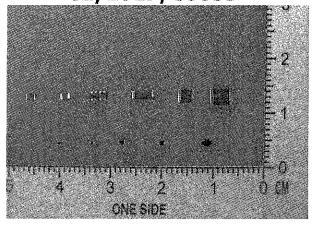
(江蘇省昆山市篷朗昆嘉高科技工業區郭澤路 / GUO-ZE ROAD, KUNJIA HI-TECH INDUSTRIAL PARK, KUN-SHAN, JIANG-SU,

(中國,江蘇省,宿遷市,泗洪縣,經濟開發區杭州路南側,建設北路東側 / THE SOUTH HANGZHOU ROAD AND THE EAST JIANSHE ROAD, ECONOMIC DEVELOPMENT ZONE, SIHONG COUNTY, SUQIANCITY, JIANGSU PROVINCE, P. R., CHINA)

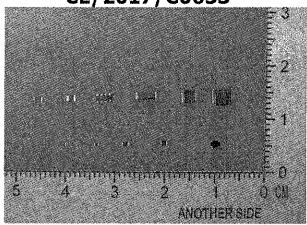
* 照片中如有箭頭標示,則表示為實際檢測之樣品/部位. *

(The tested sample / part is marked by an arrow if it's shown on the photo.)

CE/2017/C0633



CE/2017/C0633



** 報告結尾 (End of Report) **

This document is issued by the Company subject to its General Conditions of Service printed overleaf, available on request or accessible at https://www.ags.com/en/Terms-and-Conditions for electronic format documents, subject to Terms and Conditions for Electronic Documents at <a href="https://www.ags.com/en/Terms-and-Conditions/Enros-Locument.ass.com/en/Terms-and-Conditions/Enros-Locumen

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for Fixed Inductors category:

Click to view products by TAITEC manufacturer:

Other Similar products are found below:

MLZ1608M6R8WTD25 MLZ1608N6R8LT000 MLZ1608N3R3LTD25 MLZ1608N3R3LTD00 MLZ1608N150LT000 MLZ1608N150WTD00 MLZ1608M150WTD00 MLZ1608M1SWTD00 MLZ1608M1SWTD00 MLZ1608N1R5WTD00 MLZ1608N1R5WTD00 MLZ1608N1R5WTD00 MLZ1608N1R5WTD00 B82432C1333K000 PCMB053T-1R0MS PCMB053T-1R5MS PCMB104T-1R5MS CR32NP-100KC CR32NP-151KC CR32NP-180KC CR32NP-181KC CR32NP-180KC CR32NP-181KC CR32NP-390KC CR32NP-390KC CR32NP-389MC CR32NP-680KC CR32NP-820KC CR32NP-8R2MC CR43NP-390KC CR43NP-560KC CR43NP-680KC CR54NP-181KC CR54NP-470LC CR54NP-820KC CR54NP-8R5MC MGDQ4-00004-P MGDU1-00016-P MHL1ECTTP18NJ MHL1JCTTD12NJ PE-51506NL PE-53601NL PE-53630NL PE-53824SNLT PE-62892NL PE-92100NL PG0434.801NLT PG0936.113NLT PM06-2N7 PM06-39NJ HC2LP-R47-R HC3-2R2-R HC8-1R2-R